



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Stephan Grunow, et al.
Serial No.: 10/688,452
Filed: October 18, 2003

Examiner: Not Assigned
Art Unit: N/A
Docket No: TI-35917 (1207-013)

For: A STACKED INTERCONNECT STRUCTURE BETWEEN COPPER
LINES OF A SEMICONDUCTOR CIRCUIT

PRELIMINARY AMENDMENT

Mail Stop Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(A)
I hereby certify that the above correspondence is being deposited with
the U.S. Postal Service as first Class Mail in an envelope addressed to
Mail Stop Non-Fee Amendment, Commissioner for Patents, PO Box
1450, Alexandria, VA 22313-1450.

2-19-04
Date
Marianna Smith
Marianna Smith

Sir:

Please amend the above-referenced application as follows: